廣奕電子股份有限公司
Quality Electronics Co.,Ltd

Moisture Sensitivity Level (MSL)

Date : 2023/12/28

1. If devices are not handled correctly, in accordance with their MSL conditions, then they will start to naturally absorb moisture. When heated rapidly during reflow soldering, the moisture turns to steam. If it cannot escape quickly enough the pressure built up may damage the component by cracking the package moulding, aneffect known as “Popcorning”.

2. IPC/JEDEC J-STD-020C also defines device MSLs as part of the specification. MSL Level 1 is uesd for products supplied without moisture proof packaging. The products of have an MSL Level of 1.
The Table below details the MSL Levels and conditions defined byJ-STD-020C

Level Select		Floor Life		Soak Requirement			
				Standard		Accelerate Equivalent	
		Time	Condition	Time (hour)	Conditions	Time (hour)	Conditions
●	1	Unli ited	≦30℃/85%RH	168 +5/-0	85℃/85%RH	-	-
	2	1 year	≦30℃/60%RH	168 +5/-0	85℃/60%RH	-	-
	2a	4 weeks	≦30℃/60%RH	696 +5/-0	30℃/60%RH	120 +1/-0	60℃/60%RH
	3	168 hours	≦30℃/60%RH	192 +5/-0	30℃/60%RH	40 +1/-0	60℃/60%RH
	4	72 hours	≦30℃/60%RH	96 +2/-0	30℃/60%RH	20 +0.5/-0	60℃/60%RH
	5	48 hours	≦30℃/60%RH	72 +2/-0	30℃/60%RH	15 +0.5/-0	60℃/60%RH
	5a	24 hours	≦30℃/60%RH	48 +2/-0	30℃/60%RH	10 +0.5/-0	60℃/60%RH
	6	Time on Label	≦30℃/60%RH	TOL	30℃/60%RH	-	-
Note		Accelerated equivalent method is used for soak requirement.					

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